

MGPA version 2 submission status – Mark Raymond / Jamie Crooks (RAL)

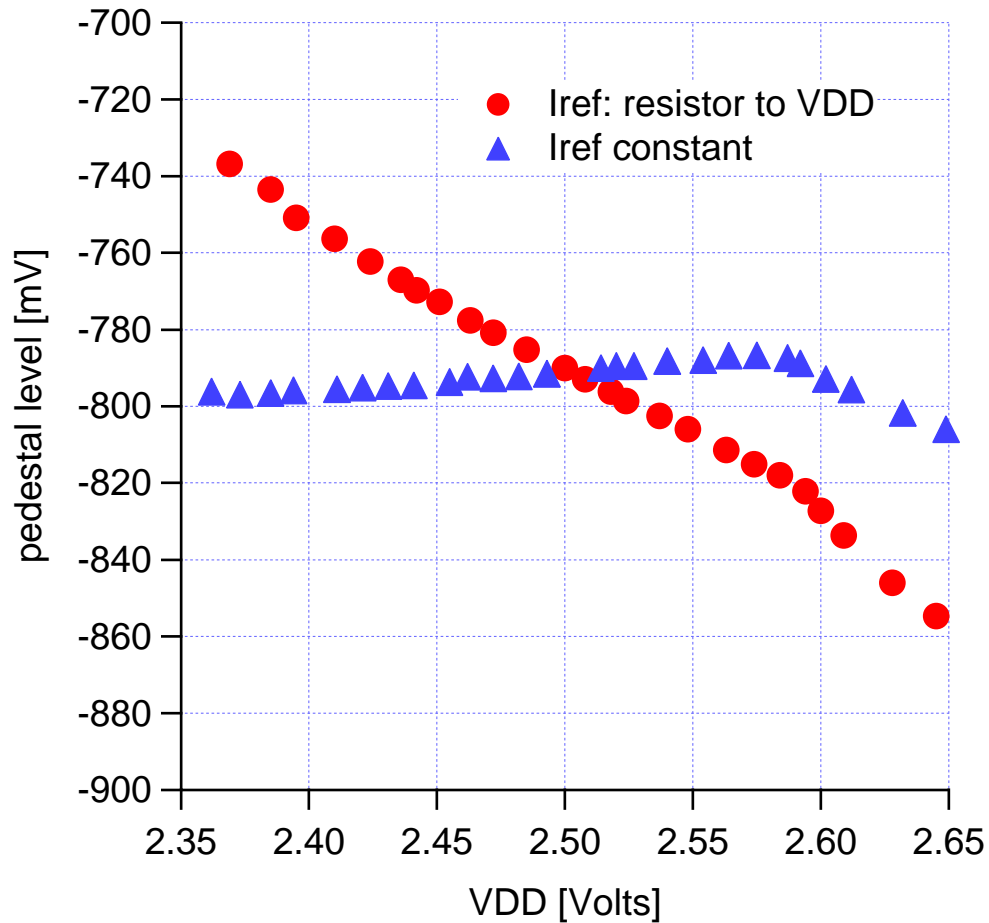
3 changes already proposed:

- 1) on-chip current reference
 - present VFE card uses external circuit
 - simple resistor to VDD -> supply voltage dependence
- 2) re-arrange digital signals to help VFE board layout
 - allow routing of CALIN line away from chip inputs
- 3) Change I2C default settings
 - set gain channel pedestals
 - set CAL mode to ON and non-zero DAC setting

1 additional change:

- use spare pads either side of present QIN pad to triplicate QIN line
 - reduces effective input inductance -> increased stability margin
 - trivial layout change, worth having

measured pedestal dependence on supply voltage



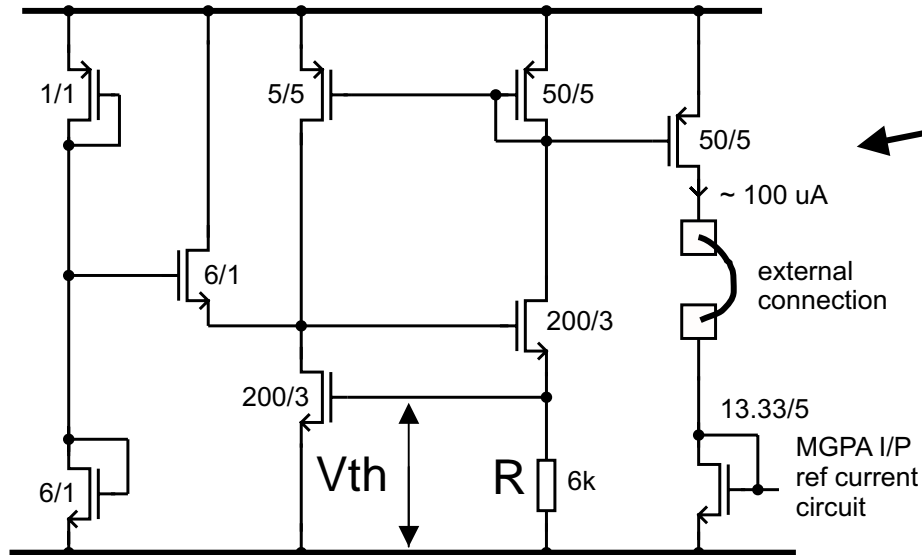
on-chip current reference

improves pedestal stability to supply drift

~ 7.5 mV VDD drift -> 1 lsb pedestal drift (if Iref const.)

(factor ~ 6 improvement on resistor to VDD)

=> worth having



on-chip current reference

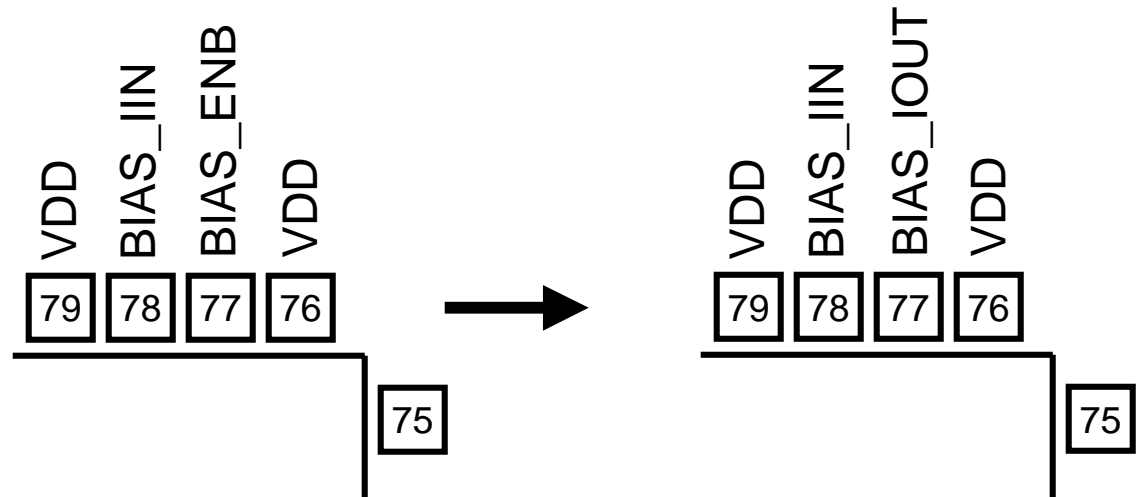
standard circuit (used before)

I_{ref} depends on V_{th} and R

=> process (but **not** supply) dependent

put circuit in corner of chip near BIAS_IIN pad

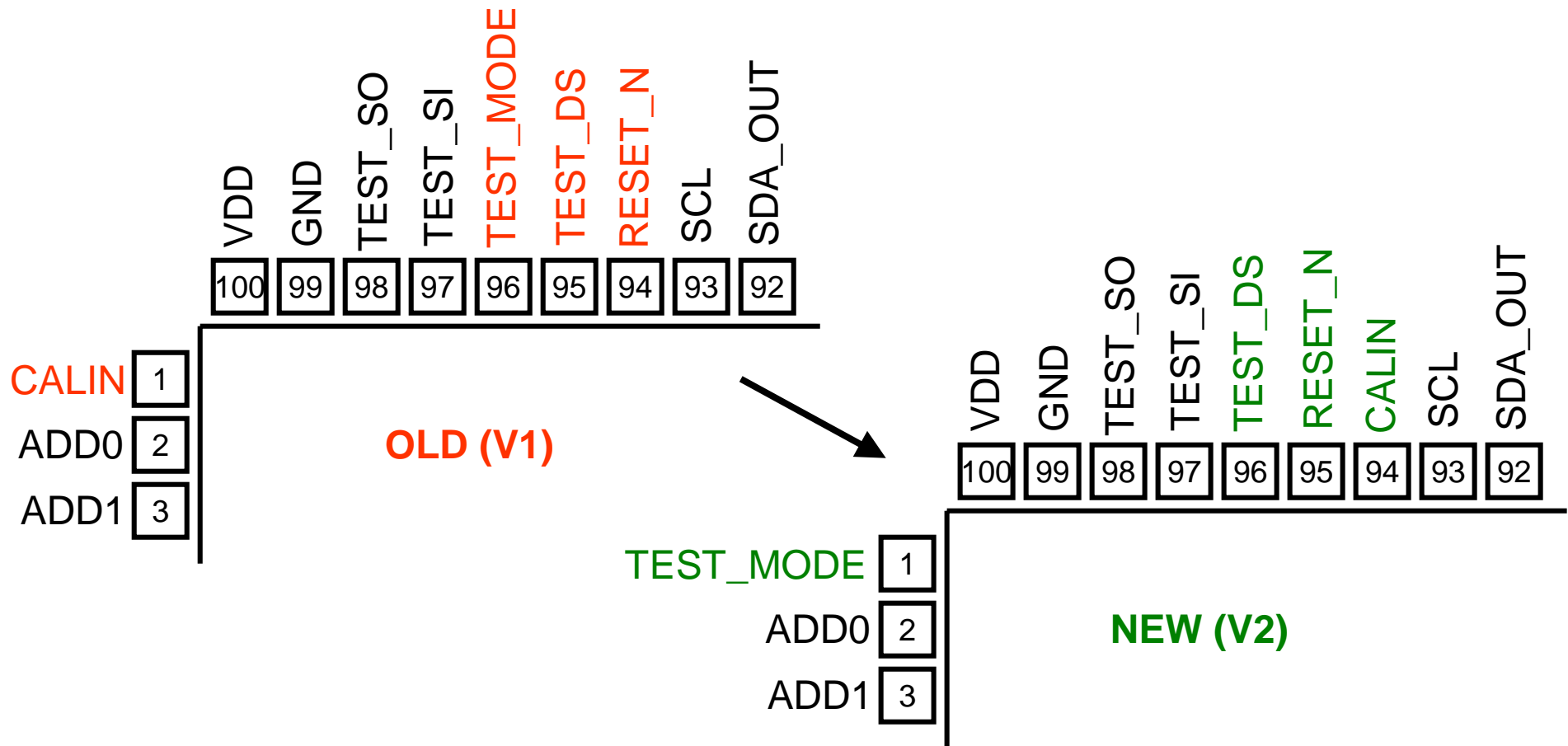
scrap BIAS_ENB function (not used) and replace by BIAS_IOUT (link on PCB)



re-arrange digital signals

allows CALIN (2.5V transition) to route well away from MGPA I/P on VFE card (1 line for all 5 chips)

=> V1 and V2 pinouts **not** compatible



change I²C default settings

user request for non-zero default settings for pedestals, cal mode ON and non-zero DAC value
chip usable (and testable) without I²C control

problem: I²C block synthesized -> don't want to re-synthesize and re-route (risk, time)

solution: can make manual changes to wiring but each bit requires several cuts/straps X 3 (triplicated registers)

=> can be done but bigger job if several bits/register

=> limit changes to one bit/register

all 3 pedestal registers default to 64

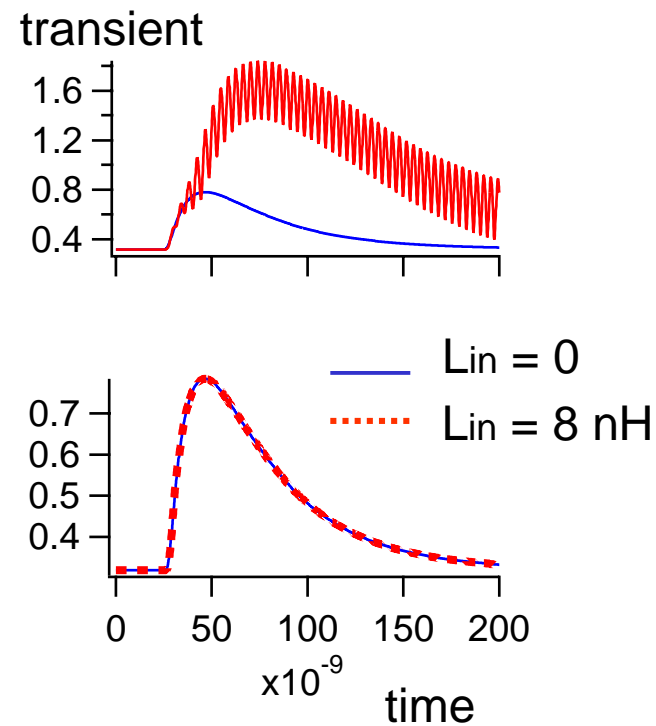
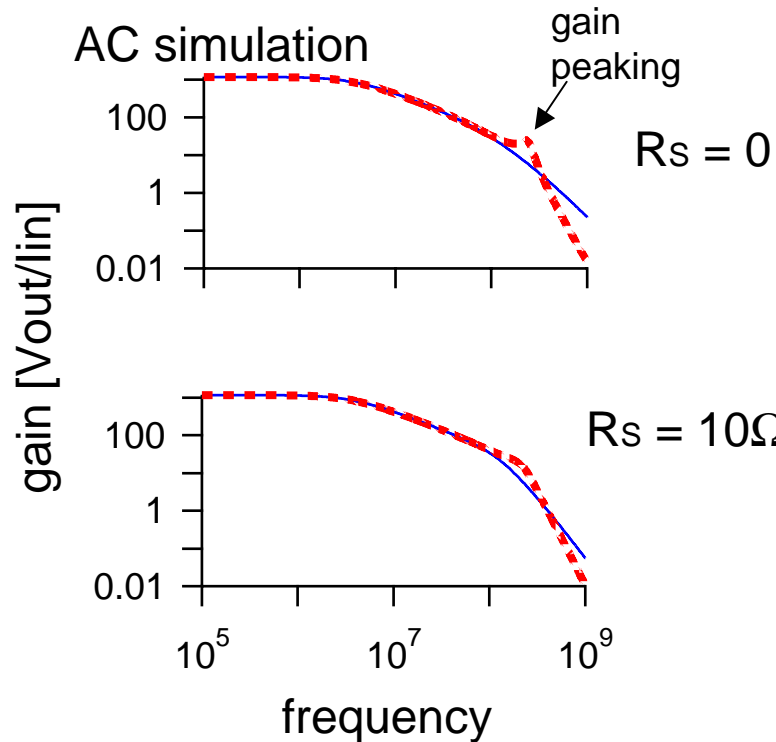
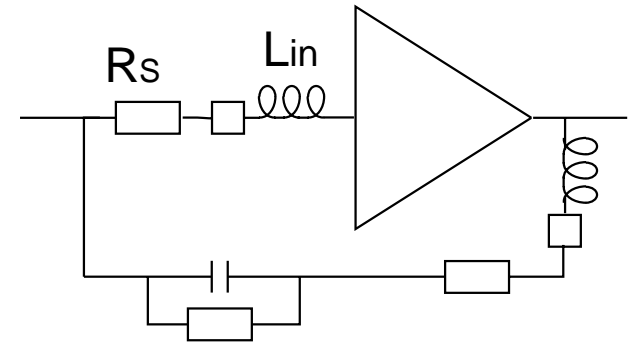
control register defaults to cal ON

DAC defaults to 4 (~ 2/3 fullscale signal on high gain range for $C_{inj} = 10 \text{ pF}$)

NOTE: process/fabrication variations => optimum pedestal setting will still require I²C

1st stage stability

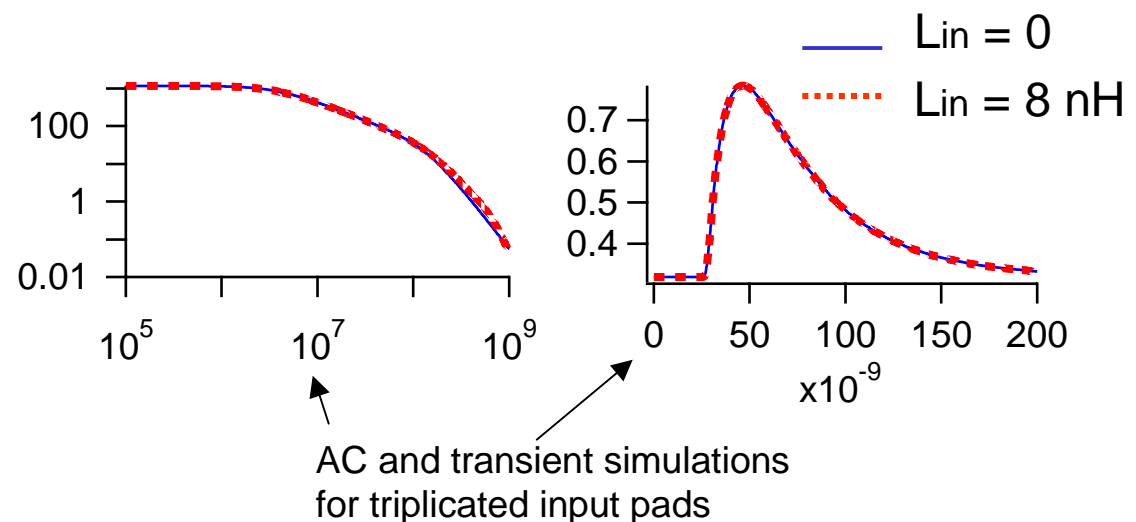
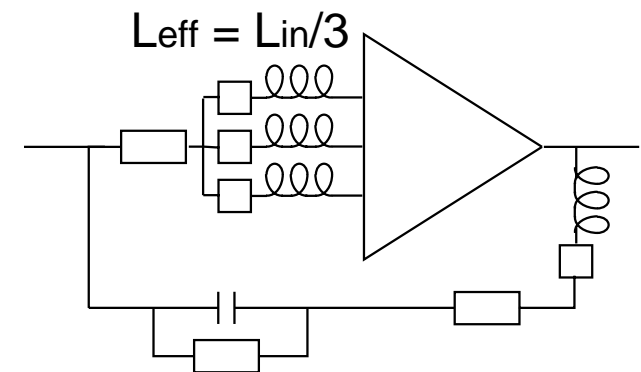
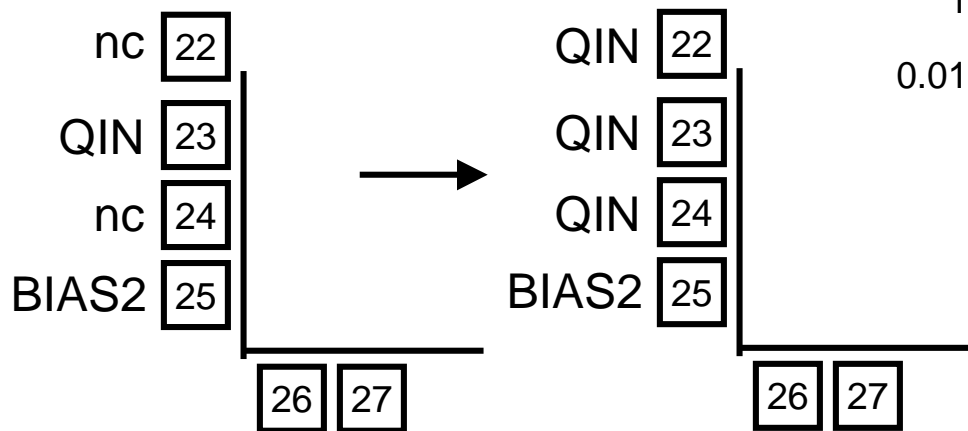
need series resistors to damp effect of parasitic L (bondwire/package)
-> effective fix for current VFE card
observed behaviour can be simulated – gain peaking in AC simulation
-> instability in transient simulation
stable if series resistor inserted



1st stage stability – any improvement possible?

yes – if make use of spare pads either side of current Qin pad
can reduce L_{in} by factor 3

minor change to wiring, no change to 1st stage layout
-> improved stability margin -> worth having



MGPA version 2 submission status summary

- 1) on-chip current reference
- 2) re-arrange digital signals to help VFE board layout
- 3) Change I2C default settings
- 4) modify QIN to 3 pads instead of 1

all layout changes completed and full DRC passed

most of simulations complete

some additional routine checks still outstanding (nothing major - won't go into details here)

estimated time required ~ only day or two more

design transmission to CERN expected at end of this week (Friday 14th November)